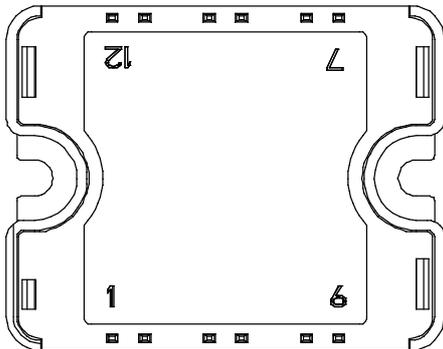
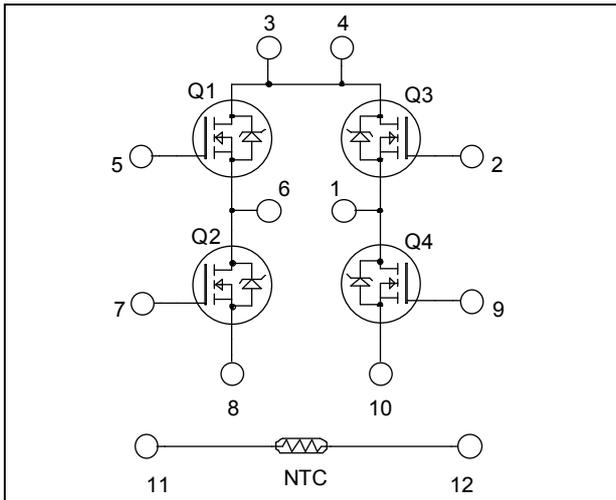


Full - Bridge Super Junction MOSFET Power Module

$V_{DSS} = 900V$
 $R_{DSon} = 120m\Omega \text{ max @ } T_j = 25^\circ C$
 $I_D = 30A \text{ @ } T_c = 25^\circ C$



Pins 3/4 must be shorted together

Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- **COOLMOS**
Power Semiconductors
 - Ultra low R_{DSon}
 - Low Miller capacitance
 - Ultra low gate charge
 - Avalanche energy rated
 - Very rugged
- Very low stray inductance
 - Symmetrical design
- Internal thermistor for temperature monitoring
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- Each leg can be easily paralleled to achieve a phase leg of twice the current capability
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{DSS}	Drain - Source Breakdown Voltage	900	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	30
		$T_c = 80^\circ C$	23
I_{DM}	Pulsed Drain current	75	A
V_{GS}	Gate - Source Voltage	± 20	V
R_{DSon}	Drain - Source ON Resistance	120	$m\Omega$
P_D	Maximum Power Dissipation	$T_c = 25^\circ C$	250
I_{AR}	Avalanche current (repetitive and non repetitive)	8.8	A
E_{AR}	Repetitive Avalanche Energy	2.9	mJ
E_{AS}	Single Pulse Avalanche Energy	1940	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} = 0V, V _{DS} = 900V	T _j = 25°C			100	μA
		V _{GS} = 0V, V _{DS} = 900V	T _j = 125°C		500		
R _{DS(on)}	Drain – Source on Resistance	V _{GS} = 10V, I _D = 26A			100	120	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} = V _{DS} , I _D = 3mA		2.5	3	3.5	V
I _{GSS}	Gate – Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0V				100	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C _{iss}	Input Capacitance	V _{GS} = 0V ; V _{DS} = 100V		6.8		nF
C _{oss}	Output Capacitance	f = 1MHz		0.33		
Q _g	Total gate Charge	V _{GS} = 10V V _{Bus} = 400V I _D = 26A		270		nC
Q _{gs}	Gate – Source Charge			32		
Q _{gd}	Gate – Drain Charge			115		
T _{d(on)}	Turn-on Delay Time	Inductive Switching (125°C) V _{GS} = 10V V _{Bus} = 600V I _D = 26A R _G = 7.5Ω		70		ns
T _r	Rise Time			20		
T _{d(off)}	Turn-off Delay Time			400		
T _f	Fall Time			25		
E _{on}	Turn-on Switching Energy	Inductive switching @ 25°C V _{GS} = 10V ; V _{Bus} = 600V I _D = 26A ; R _G = 7.5Ω		1.5		mJ
E _{off}	Turn-off Switching Energy			0.75		
E _{on}	Turn-on Switching Energy	Inductive switching @ 125°C V _{GS} = 10V ; V _{Bus} = 600V I _D = 26A ; R _G = 7.5Ω		2.1		mJ
E _{off}	Turn-off Switching Energy			0.85		

Source - Drain diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
I _S	Continuous Source current (Body diode)		T _c = 25°C			30	A
			T _c = 80°C			23	
V _{SD}	Diode Forward Voltage	V _{GS} = 0V, I _S = - 26A			0.8	1.2	V
t _{rr}	Reverse Recovery Time	I _S = - 26A V _R = 400V	T _j = 25°C		920		ns
Q _{rr}	Reverse Recovery Charge	di _S /dt = 200A/μs	T _j = 25°C		30		μC

Thermal and package characteristics

Symbol	Characteristic	Min	Typ	Max	Unit	
R _{thJC}	Junction to Case Thermal Resistance			0.50	°C/W	
V _{ISOL}	RMS Isolation Voltage, any terminal to case t=1 min, 50/60Hz	4000			V	
T _J	Operating junction temperature range	-40		150	°C	
T _{STG}	Storage Temperature Range	-40		125		
T _C	Operating Case Temperature	-40		100		
Torque	Mounting torque	To heatsink	M4	2	3	N.m
Wt	Package Weight			80		g

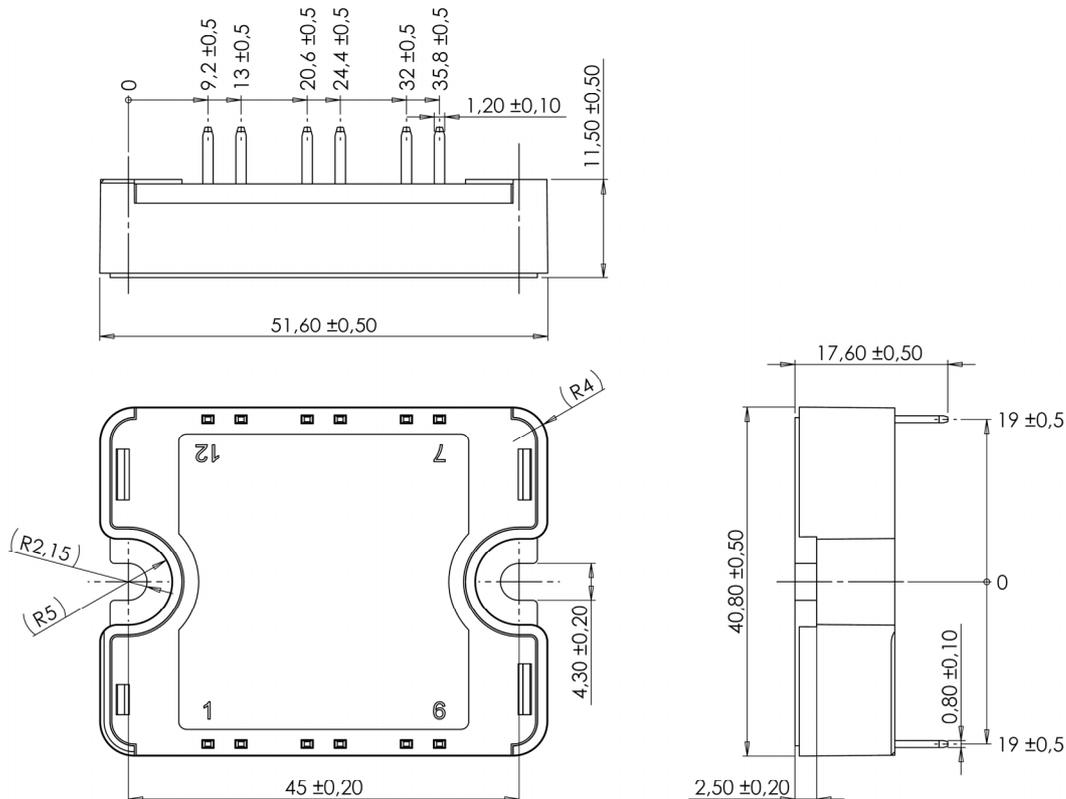
Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic	Min	Typ	Max	Unit
R ₂₅	Resistance @ 25°C		50		kΩ
ΔR ₂₅ /R ₂₅			5		%
B _{25/85}	T ₂₅ = 298.15 K		3952		K
ΔB/B	T _C = 100°C		4		%

$$R_T = \frac{R_{25}}{\exp \left[B_{25/85} \left(\frac{1}{T_{25}} - \frac{1}{T} \right) \right]}$$

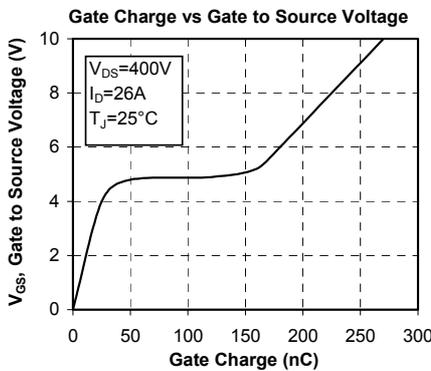
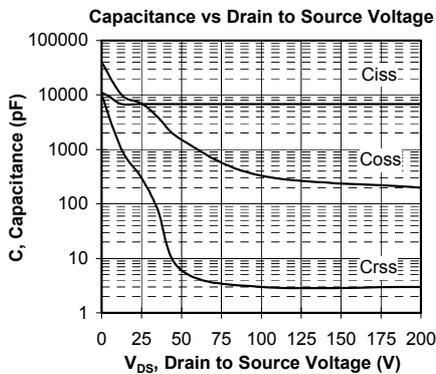
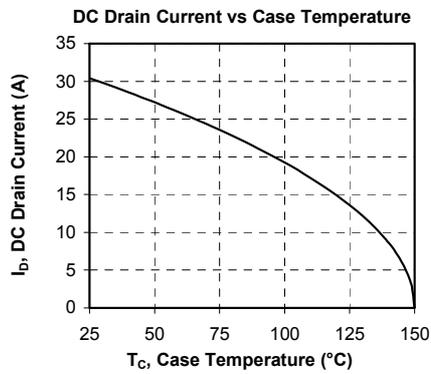
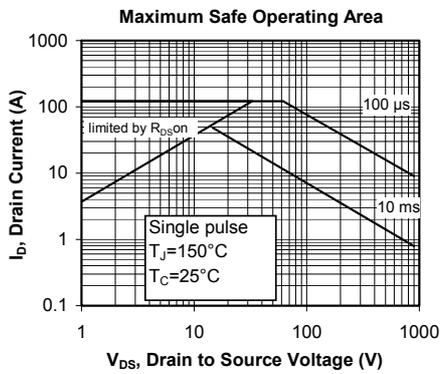
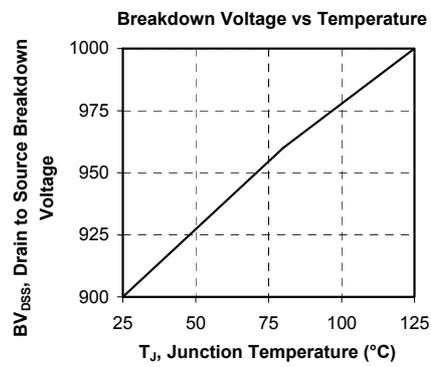
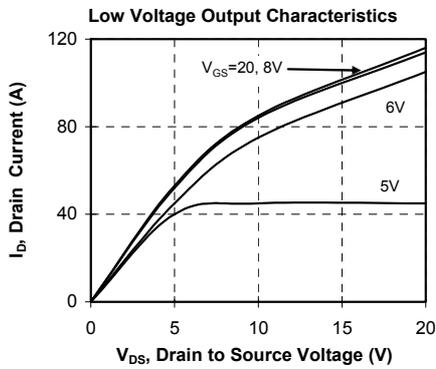
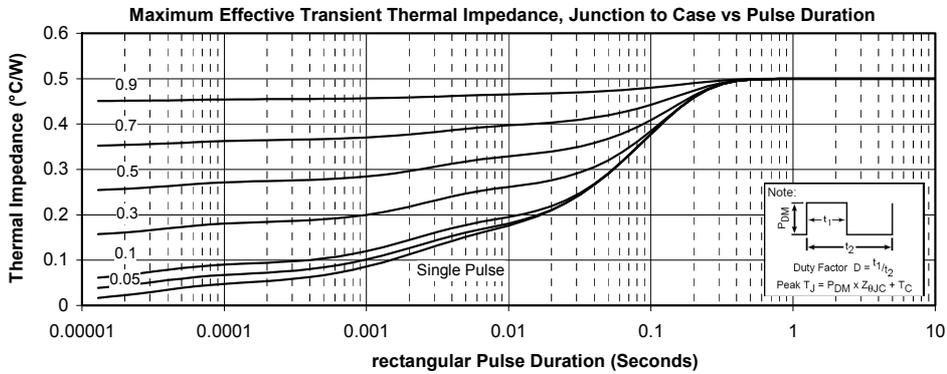
T: Thermistor temperature
 R_T: Thermistor value at T

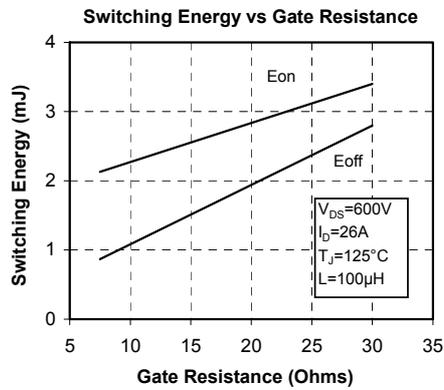
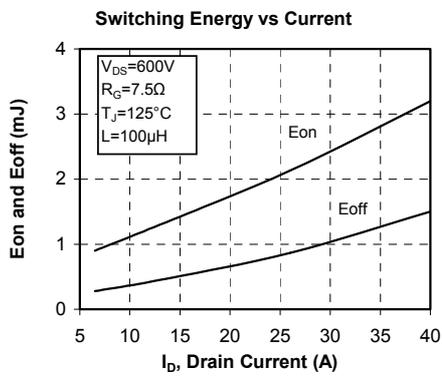
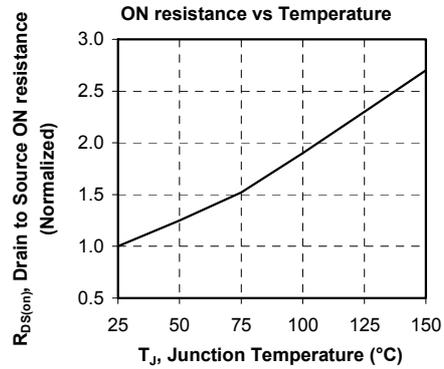
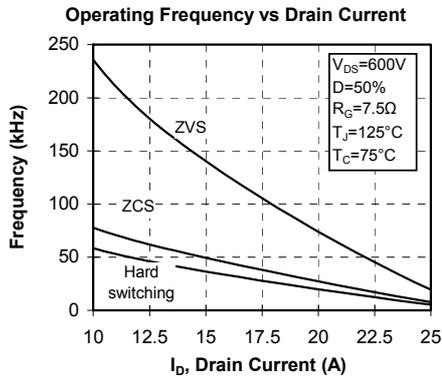
SP1 Package outline (dimensions in mm)



See application note 1904 - Mounting Instructions for SP1 Power Modules on www.microsemi.com

Typical performance Curve





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